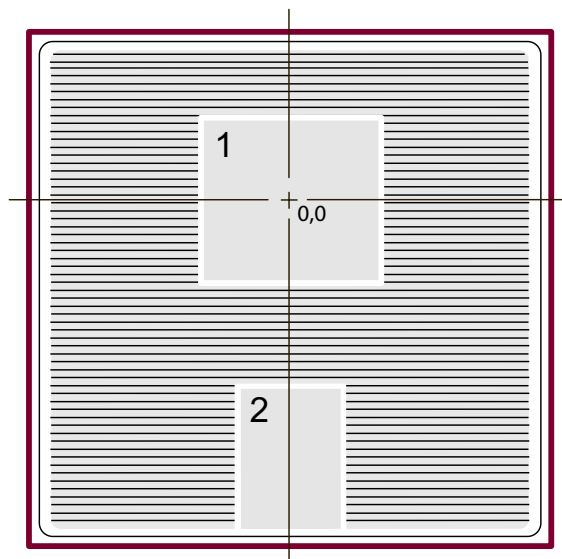


Pad Layout



Backside: Drain

Die Specifications

Device	Die Dimensions			Back Side Metal	Back Side	Bonding Pad Material
	Length ¹ (mils)	Width ¹ (mils)	Thickness (mils)			
TN2640	70	70	11 ± 1.5	Au	Drain	Al/Cu/Si

Bonding Pad Description

Pad #	Function	x Position ² (mils)	y Position ² (mils)	x Size (mils)	y Size (mils)
1	Source	0	0	13.1	10.6
2	Gate	0	-29.7	6.5	9.9

Notes:

1. Maximum values.
2. Position referenced to center of pad.

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